



High-Speed Precision *Difet*[®] OPERATIONAL AMPLIFIER

FEATURES

- WIDE BANDWIDTH: 6.5MHz
- HIGH SLEW RATE: 35V/ μ s
- LOW OFFSET: $\pm 250\mu$ V max
- LOW BIAS CURRENT: $\pm 1\mu$ A max
- FAST SETTLING TIME: 1 μ s to 0.01%
- UNITY-GAIN STABLE

APPLICATIONS

- PRECISION INSTRUMENTATION
- OPTOELECTRONICS
- SONAR, ULTRASOUND
- PROFESSIONAL AUDIO EQUIPMENT
- MEDICAL EQUIPMENT
- DATA CONVERSION

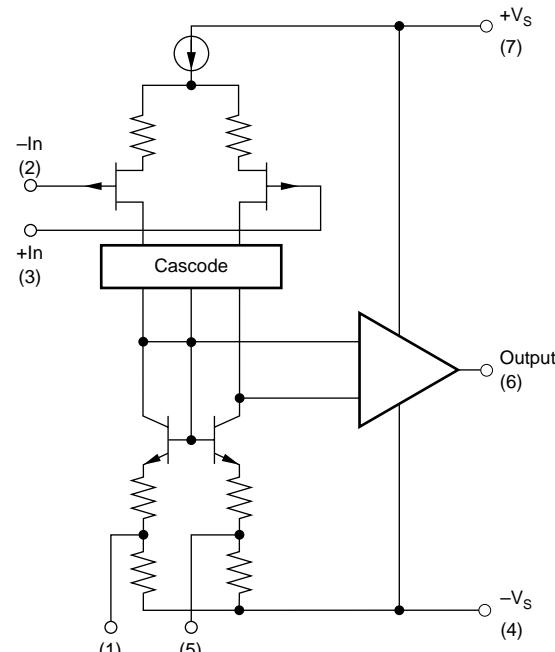
DESCRIPTION

The OPA602 is a precision, wide bandwidth FET operational amplifier. Monolithic **Difet** (dielectrically isolated FET) construction provides an unusual combination of high-speed and accuracy.

Its wide-bandwidth design minimizes dynamic errors. High slew rate and fast settling time allow accurate signal processing in pulse and data conversion applications. Wide bandwidth and low distortion minimize AC errors. All specifications are rated with a $1\text{k}\Omega$ resistor in parallel with 500pF load. The OPA602 is unity-gain stable and easily drives capacitive loads up to 1500pF .

Laser-trimmed input circuitry provides offset voltage and drift performance normally associated with precision bipolar op amps. **Difet** construction achieves extremely low input bias currents (1pA max) without compromising input voltage noise.

The OPA602's unique input cascode circuitry maintains low input bias current and precise input characteristics over its full input common-mode voltage range.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

ABSOLUTE MAXIMUM RATINGS⁽¹⁾

Supply Voltage	$\pm 18V_{DC}$
Internal Power Dissipation ($T_J \leq +175^{\circ}C$)	1000mW
Differential Input Voltage	Total V_S
Input Voltage Range	$\pm V_S$
Storage Temperature Range	
P and U Packages	$-40^{\circ}C$ to $+125^{\circ}C$
Operating Temperature Range	$-25^{\circ}C$ to $+85^{\circ}C$
P and U Packages	$-25^{\circ}C$ to $+85^{\circ}C$
Lead Temperature	
U Package, SO (3s)	$+260^{\circ}C$
Output Short-Circuit to Ground ($+25^{\circ}C$)	Continuous
Junction Temperature	$+175^{\circ}C$

NOTE: (1) Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. Exposure to absolute maximum conditions for extended periods may affect device reliability.



ELECTROSTATIC DISCHARGE SENSITIVITY

This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

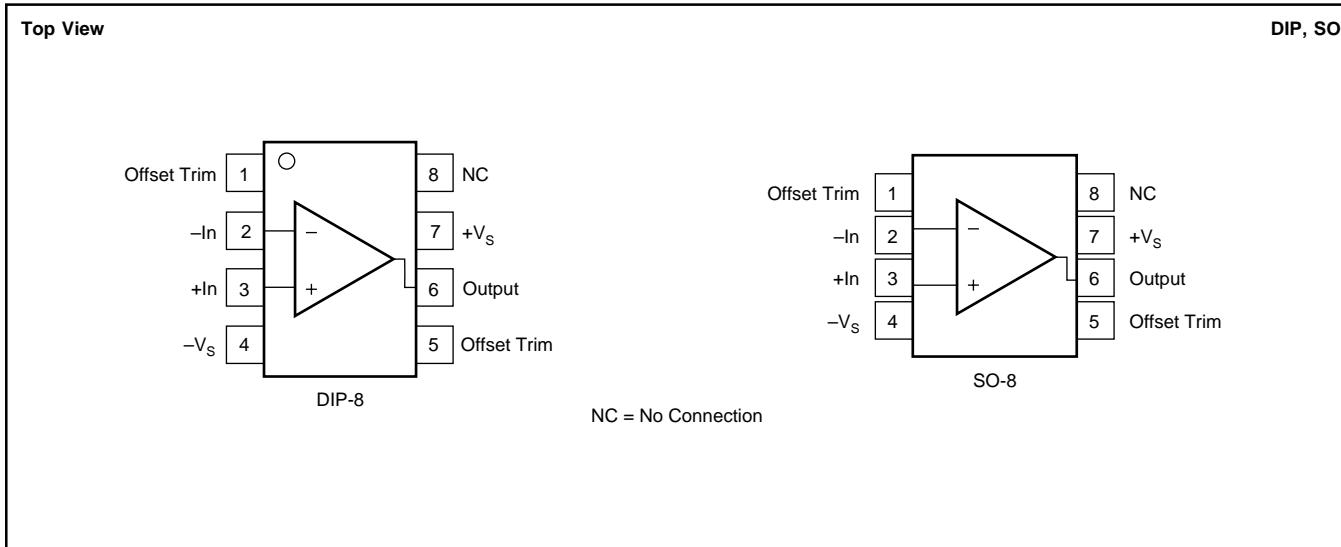
ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

PACKAGE/ORDERING INFORMATION

PRODUCT	OFFSET VOLTAGE MAX (μV) AT $25^{\circ}C$	PACKAGE-LEAD	PACKAGE DESIGNATOR ⁽¹⁾	SPECIFIED TEMPERATURE RANGE	PACKAGE MARKING	ORDERING NUMBER	TRANSPORT MEDIA, QUANTITY
OPA602AP	± 2000	DIP-8	P	$-25^{\circ}C$ to $+85^{\circ}C$	602AP	602AP	Tubes, 50
OPA602BP	± 1000	"	"	"	602BP	602BP	Tubes, 50
OPA602AU	± 3000	SO-8	D	$-25^{\circ}C$ to $+85^{\circ}C$	602AU	602AU	Tubes, 100

NOTE: (1) For the most current specifications and package information, refer to our web site at www.ti.com.

PIN CONFIGURATIONS



ELECTRICAL CHARACTERISTICS

At $V_S = \pm 15V_{DC}$ and $T_A = +25^\circ C$, unless otherwise noted.

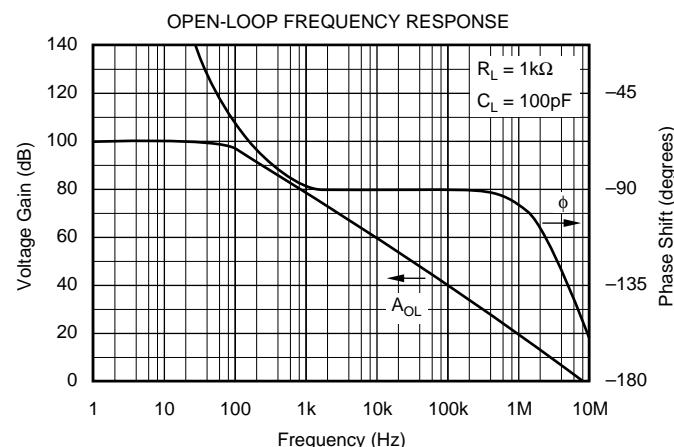
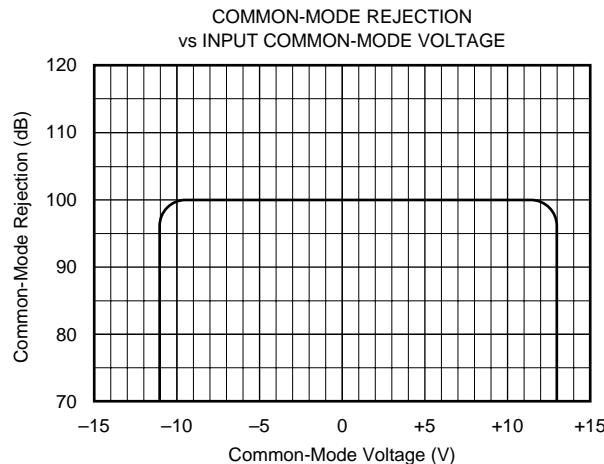
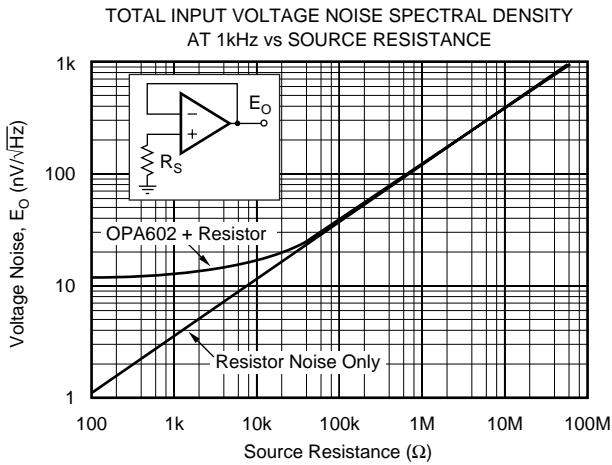
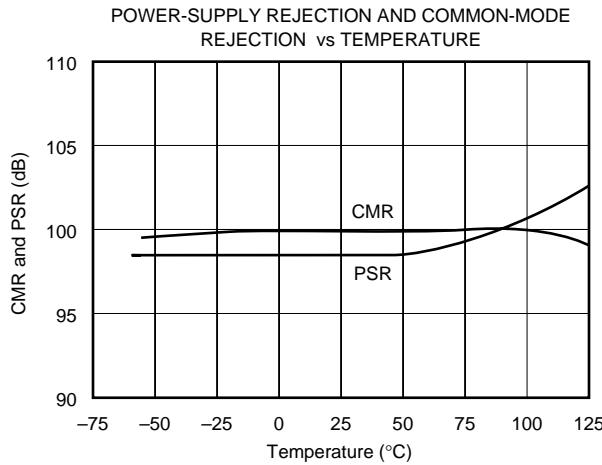
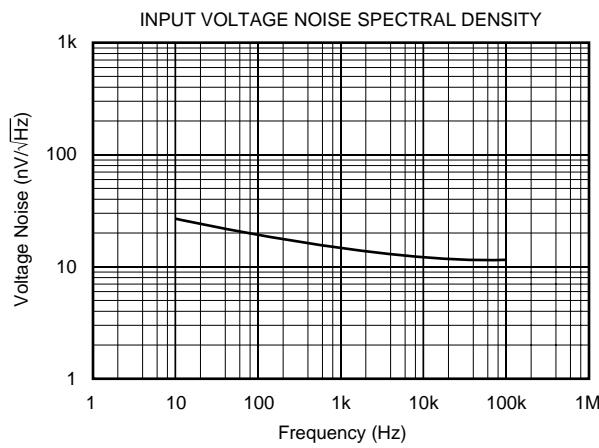
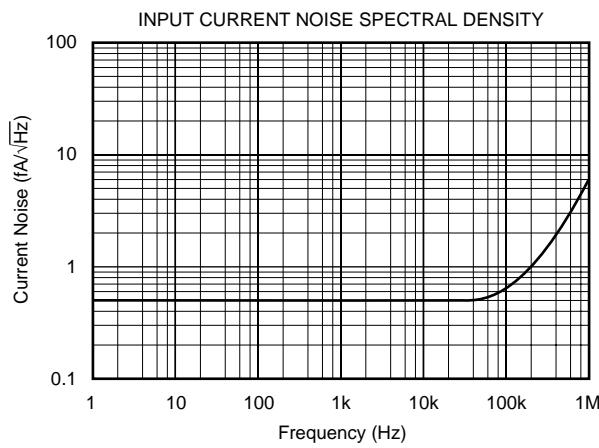
PARAMETER	CONDITIONS	OPA602BP			OPA602AP, AU			UNITS
		MIN	TYP	MAX	MIN	TYP	MAX	
INPUT NOISE								
Voltage:								
$f_O = 10Hz$		23				*		nV/\sqrt{Hz}
$f_O = 100Hz$		19				*		nV/\sqrt{Hz}
$f_O = 1kHz$		13				*		nV/\sqrt{Hz}
$f_O = 10kHz$		12				*		nV/\sqrt{Hz}
$f_B = 10Hz$ to $10kHz$		1.4				*		μV_{rms}
$f_B = 0.1Hz$ to $10Hz$		0.95				*		μV_{p-p}
Current:								
$f_B = 0.1Hz$ to $10Hz$		12				*		fA_{p-p}
$f_O = 0.1Hz$ to $20kHz$		0.6				*		fA/\sqrt{Hz}
OFFSET VOLTAGE								
Input Offset Voltage:								
P Package		0.5	1			1		mV
U Package						1	2	mV
Over Specified Temperature								
P, U Packages		± 0.75	± 1.5			± 1.5		mV
Average Drift ⁽¹⁾		± 3	± 5			*		$\mu V/^\circ C$
Supply Rejection		100				*	± 15	dB
BIAS CURRENT								
Input Bias Current	$V_{CM} = 0V_{DC}$							
Over Specified Temperature		± 1	± 2			± 2	± 10	pA
		± 20	± 200			± 20	± 500	pA
OFFSET CURRENT								
Input Offset Current	$V_{CM} = 0V_{DC}$							
Over Specified Temperature		0.5	2			1	10	pA
		20	200			20	500	pA
INPUT IMPEDANCE								
Differential				$10^{13} \parallel 1$				$\Omega \parallel pF$
Common-Mode				$10^{14} \parallel 3$				$\Omega \parallel pF$
INPUT VOLTAGE RANGE								
Common-Mode Input Range	$V_{IN} = \pm 10V_{DC}$	± 10.2	$+13, -11$			*		V
Common-Mode Rejection		88	100			75	*	dB
OPEN-LOOP GAIN, DC								
Open-Loop Voltage Gain	$R_L \geq 1k\Omega$	88	100			75	*	
FREQUENCY RESPONSE								
Gain Bandwidth								MHz
Full-Power Response	Gain = 100	4	6.5			3.5	*	
Slew Rate	20Vp-p, $R_L = 1k\Omega$		570			20	*	kHz
Settling Time:	$V_O = \pm 10V, R_L = 1k\Omega$	24	35					$V/\mu s$
0.1%								
0.01%	Gain = -1, $R_L = 1k\Omega$		0.6					μs
	$C_L = 500pF, 10V Step$		1.0					μs
RATED OUTPUT								
Voltage Output	$R_L = 1k\Omega$	± 11.5	$+12.9, -13.8$			± 11	*	V
Current Output	$V_O = \pm 10V_{DC}$	± 15	± 20			*	*	mA
Output Resistance	1MHz, Open Loop		80			*	*	Ω
Load Capacitance Stability	Gain = +1		1500			*	*	pF
Short-Circuit Current		± 30	± 50			± 25	*	mA
POWER SUPPLY								
Rated Voltage								V_{DC}
Voltage Range, Derated Performance								V_{DC}
Current, Quiescent	$I_O = 0mADC$	± 5	± 15	± 18		*	*	mA
Over Specified Temperature			3	4		*	*	mA
			3.5	4.5		*	*	mA
TEMPERATURE RANGE								
Specification	Ambient Temperature	-25		+85		*		$^\circ C$
Operating:		-25		+85		*		$^\circ C$
P, U Packages								
Storage:		-40		+125		*		$^\circ C$
P, U Packages		200				*		
θ_{JA}							*	$^\circ C/W$

* Same specifications as OPA602BP.

NOTE: (1) OPA602AP, AU ensured by design with a 99% confidence level.

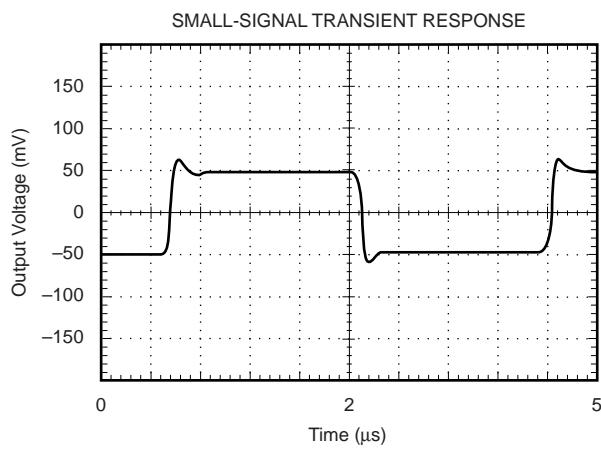
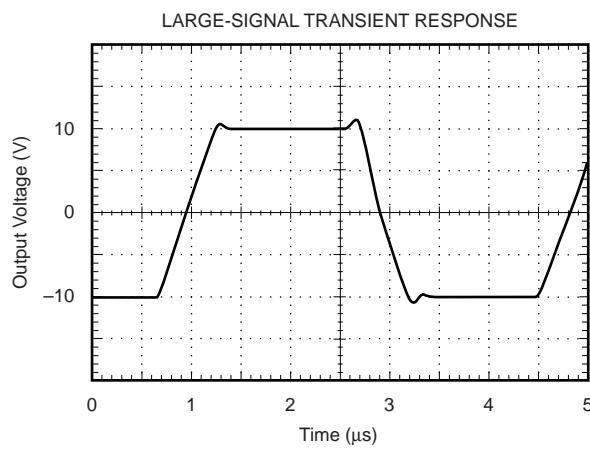
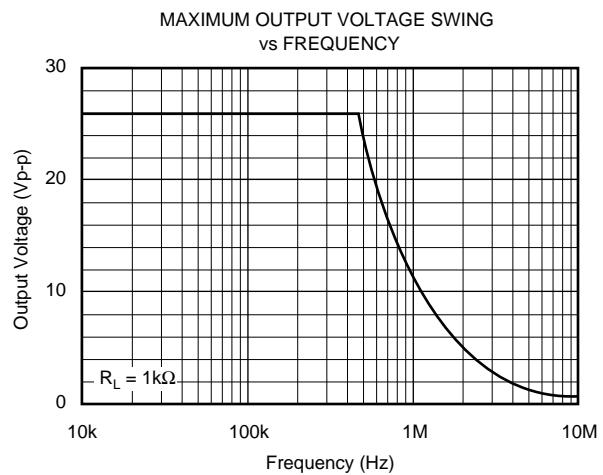
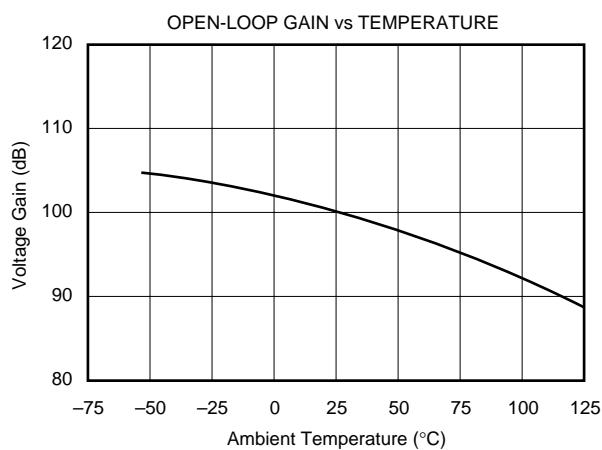
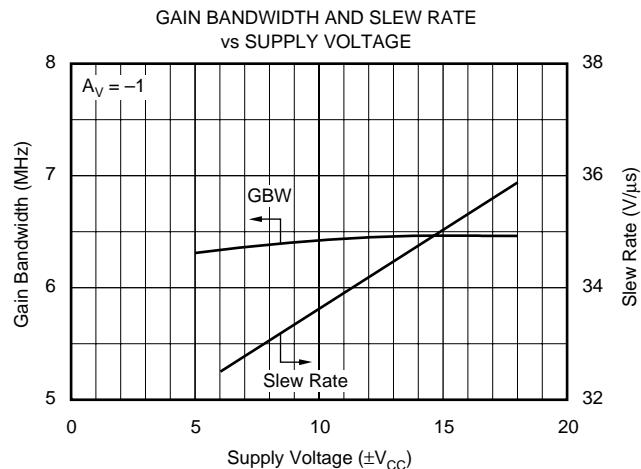
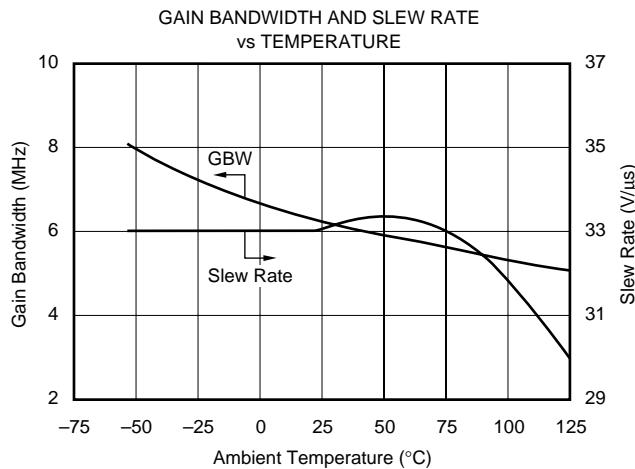
TYPICAL CHARACTERISTICS

At $T_A = +25^\circ\text{C}$ and $V_S = \pm 15\text{V}_{\text{DC}}$, unless otherwise noted.



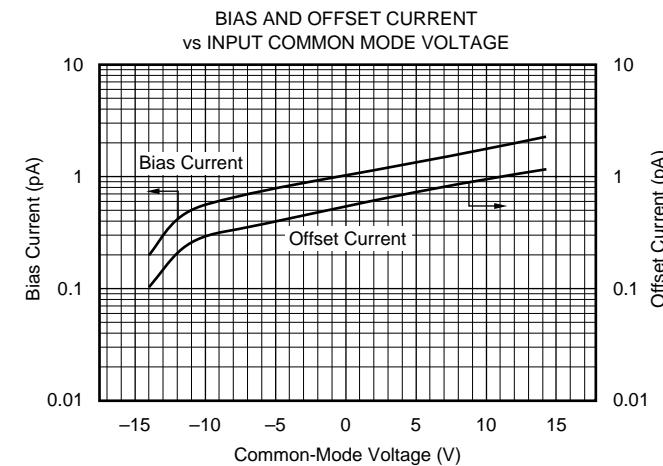
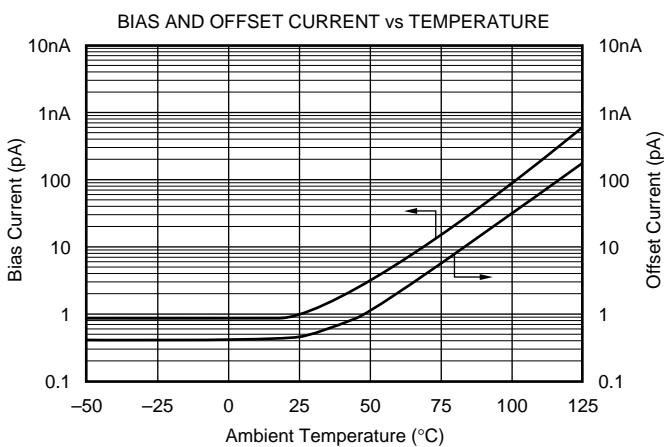
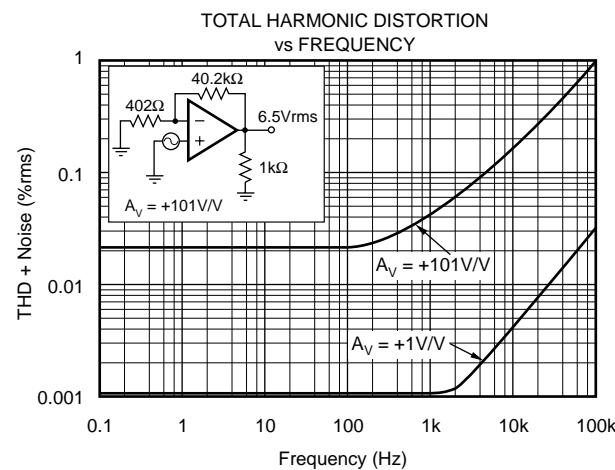
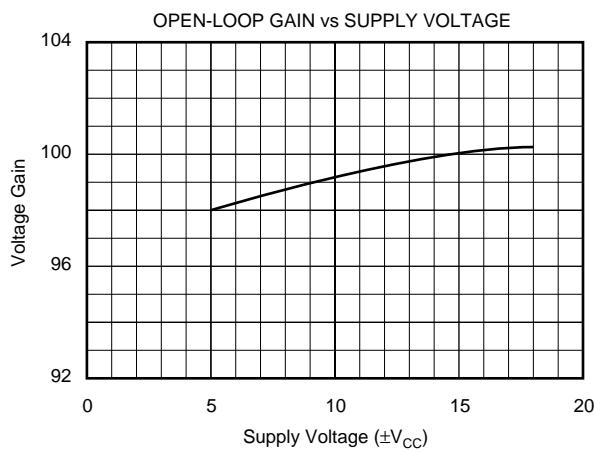
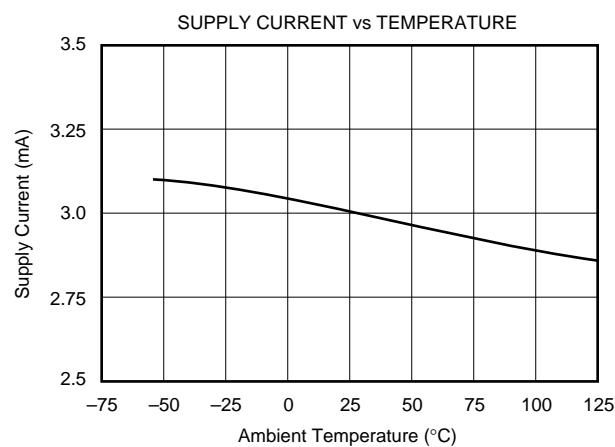
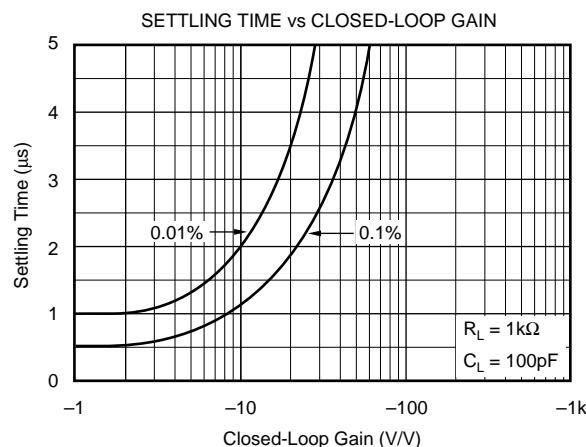
TYPICAL CHARACTERISTICS (Cont.)

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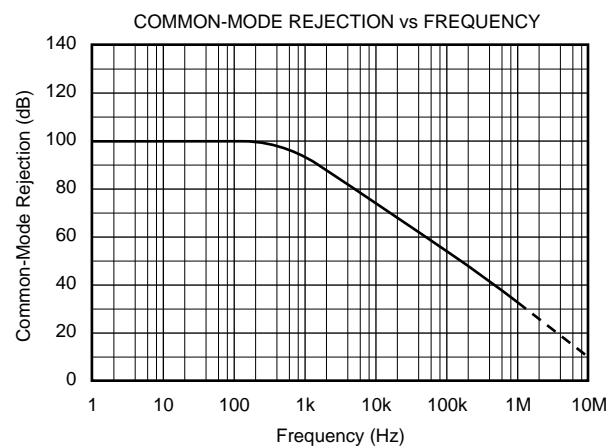
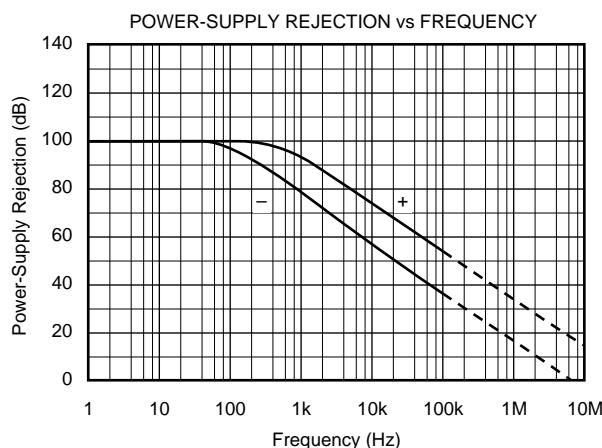
TYPICAL CHARACTERISTICS (Cont.)

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TYPICAL CHARACTERISTICS (Cont.)

At $T_A = +25^\circ\text{C}$ and $V_S = \pm 15\text{V}_{\text{DC}}$, unless otherwise noted.



APPLICATIONS INFORMATION

Unity-gain stability with good phase margin and excellent output drive characteristics bring freedom from the subtle problems associated with other high-speed amplifiers. However, as with any high-speed, wide bandwidth circuitry, careful circuit layout will ensure best performance. Make short, direct interconnections and avoid stray wiring capacitance—especially at the inverting input pin.

Power supplies should be bypassed with good high-frequency capacitors positioned close to the op amp pins. In most cases $0.1\mu\text{F}$ ceramic capacitors are adequate. Applications with heavier loads and fast transient waveforms may benefit from use of additional $1.0\mu\text{F}$ tantalum bypass capacitors.

INPUT BIAS CURRENT GUARDING

Leakage currents across printed circuit boards can easily exceed the input bias current of the OPA602. A circuit board “guard” pattern, as shown in Figure 1, is an effective solution to difficult leakage problems. This guard pattern must be repeated on all layers of a multilayer board. By surrounding critical high impedance input circuitry with a low impedance circuit connection at the same potential, leakage currents will flow harmlessly to the low-impedance node.

Input bias current may also be degraded by improper handling or cleaning. Contamination from handling parts and circuit boards may be cleaned with appropriate solvents and deionized water. Each rinsing operation should be followed by a 30-minute bake at $+85^\circ\text{C}$.

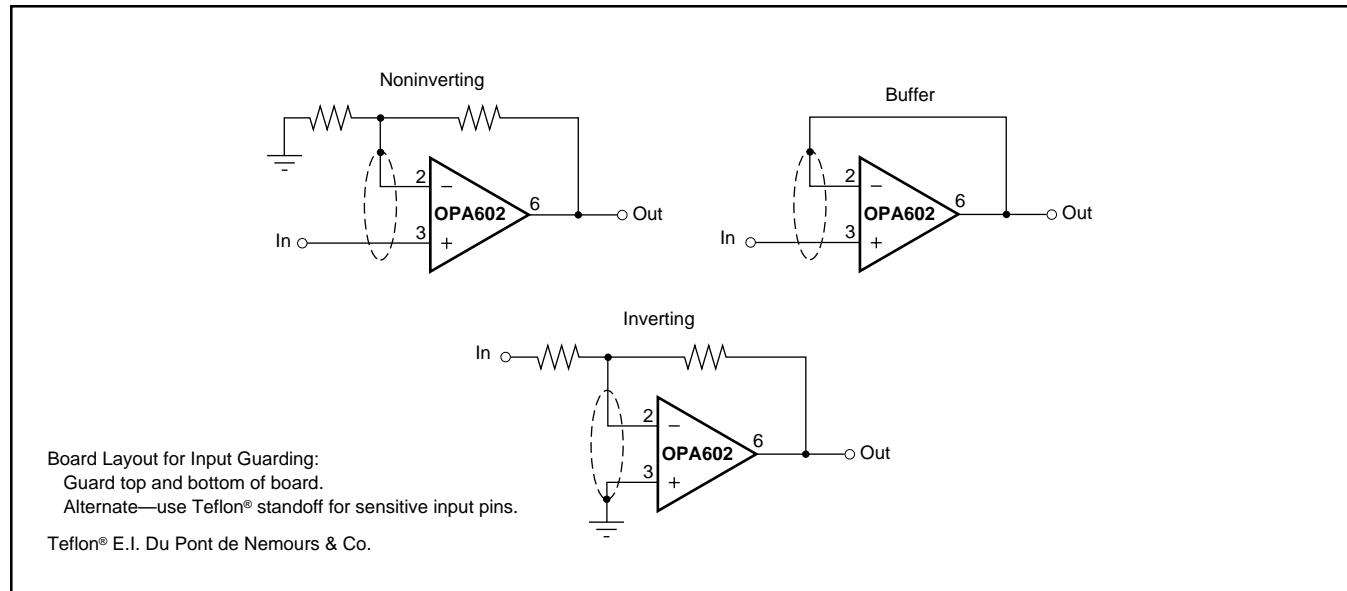


FIGURE 1. Connection of Input Guard.

APPLICATION CIRCUITS

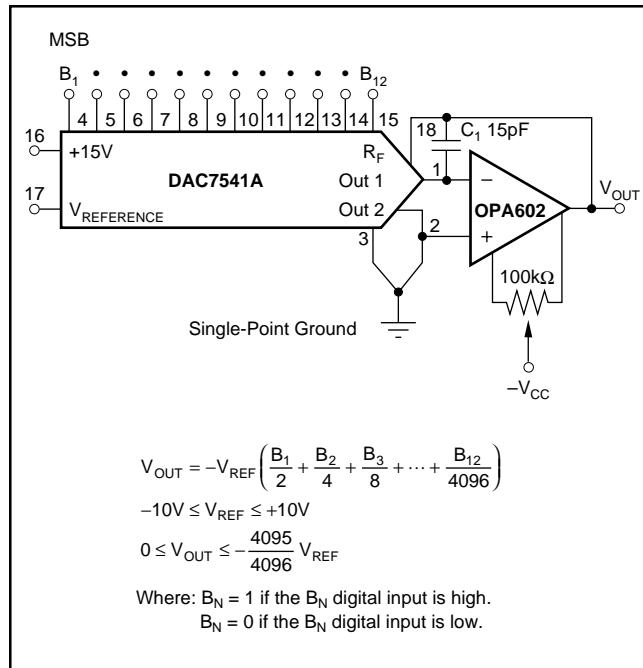
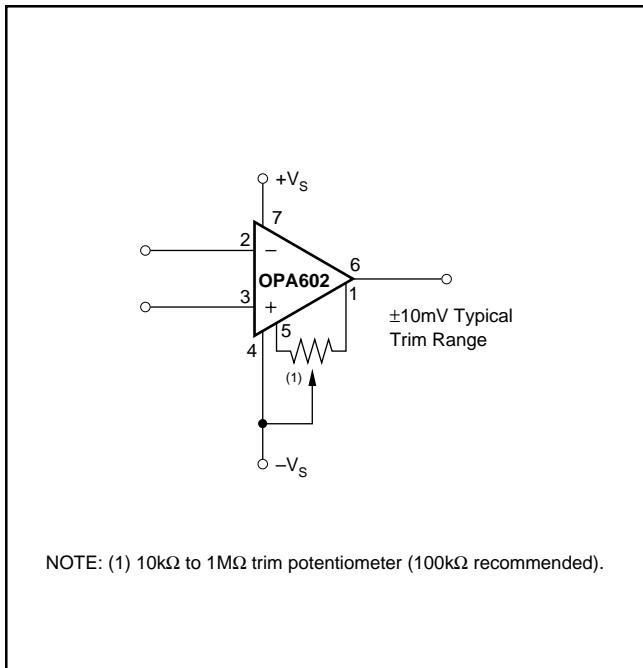


FIGURE 2. Offset Voltage Trim.

FIGURE 3. Voltage Output Digital-to-Analog Converter.

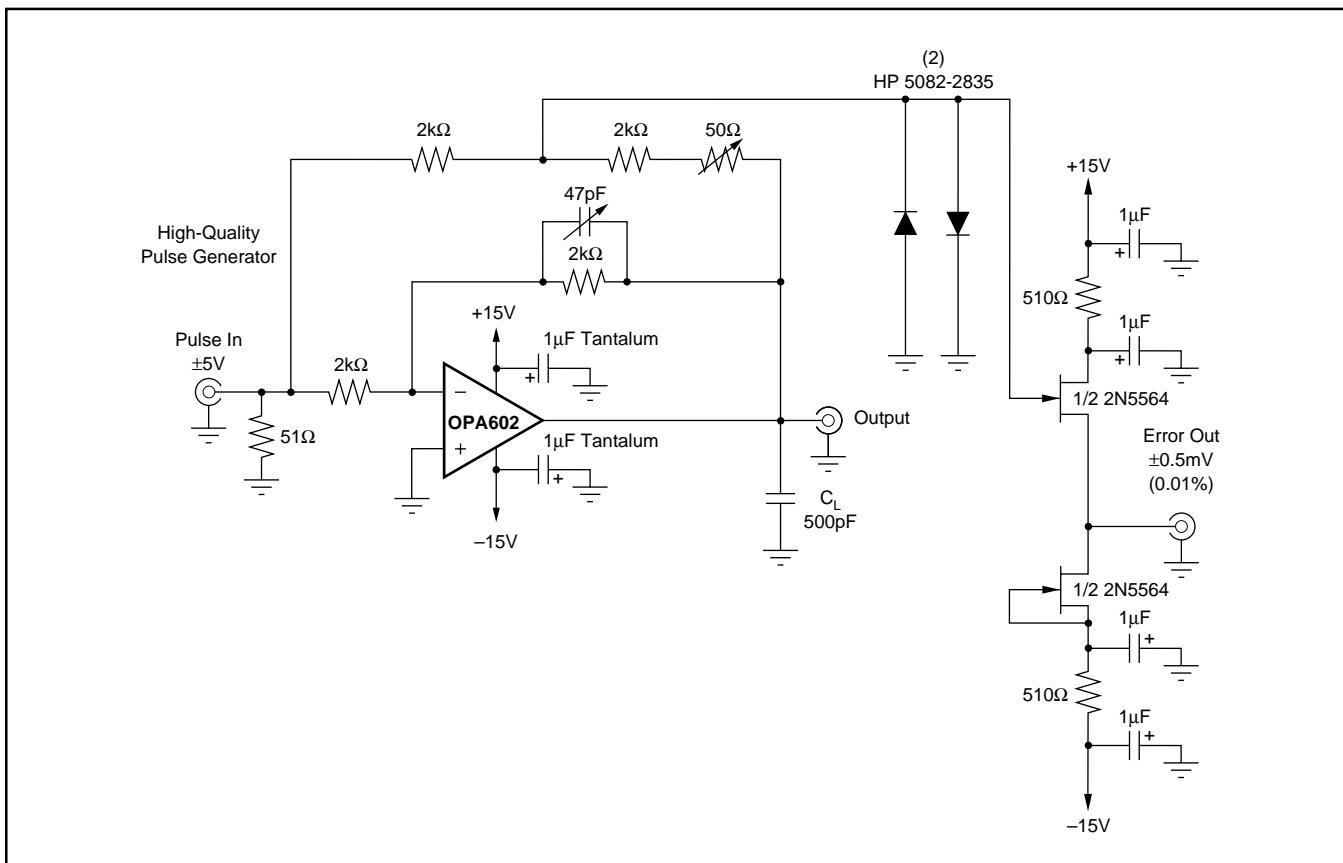
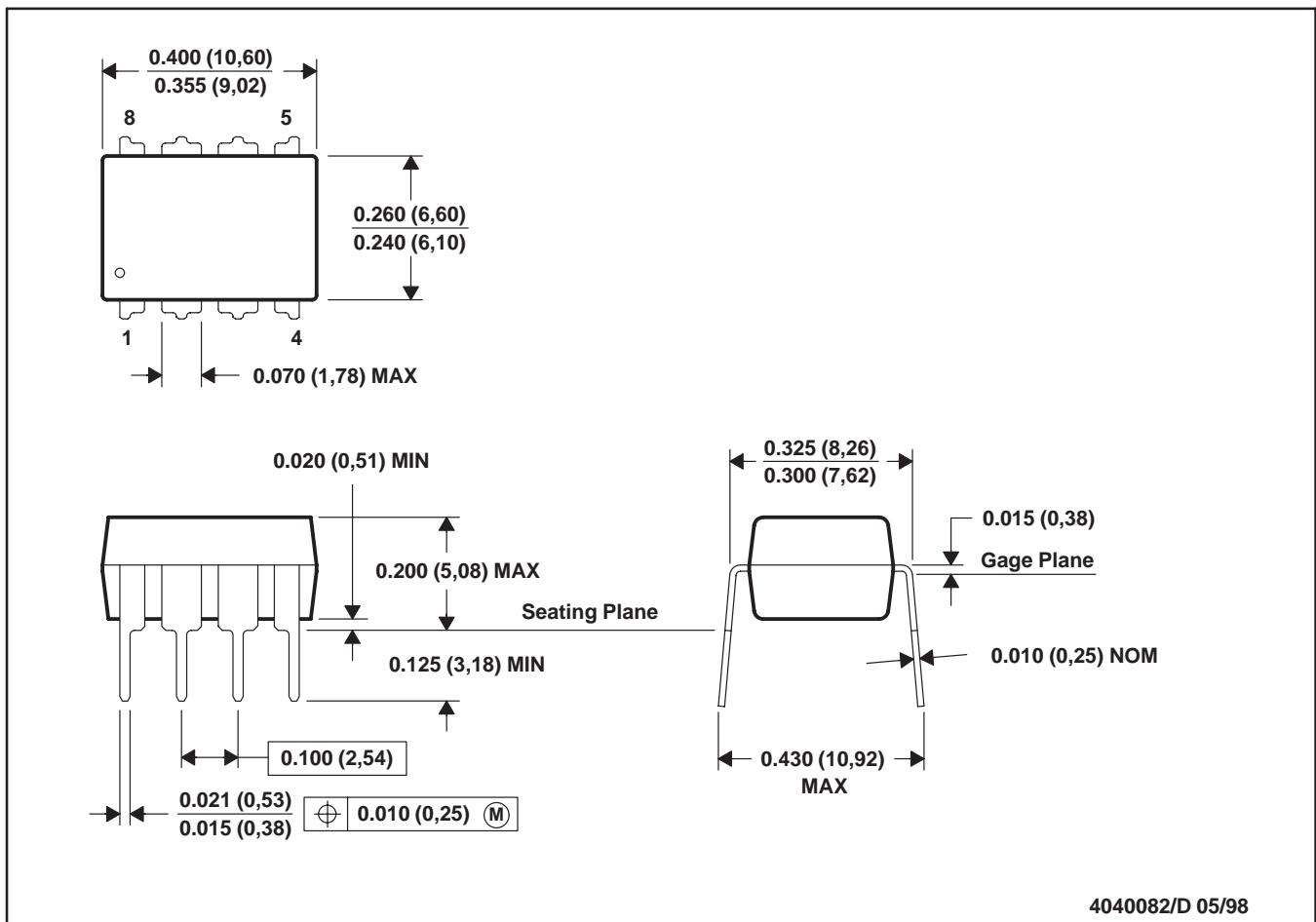


FIGURE 4. Settling Time and Slew Rate Test Circuit.

PACKAGE DRAWINGS

P (R-PDIP-T8)

PLASTIC DUAL-IN-LINE



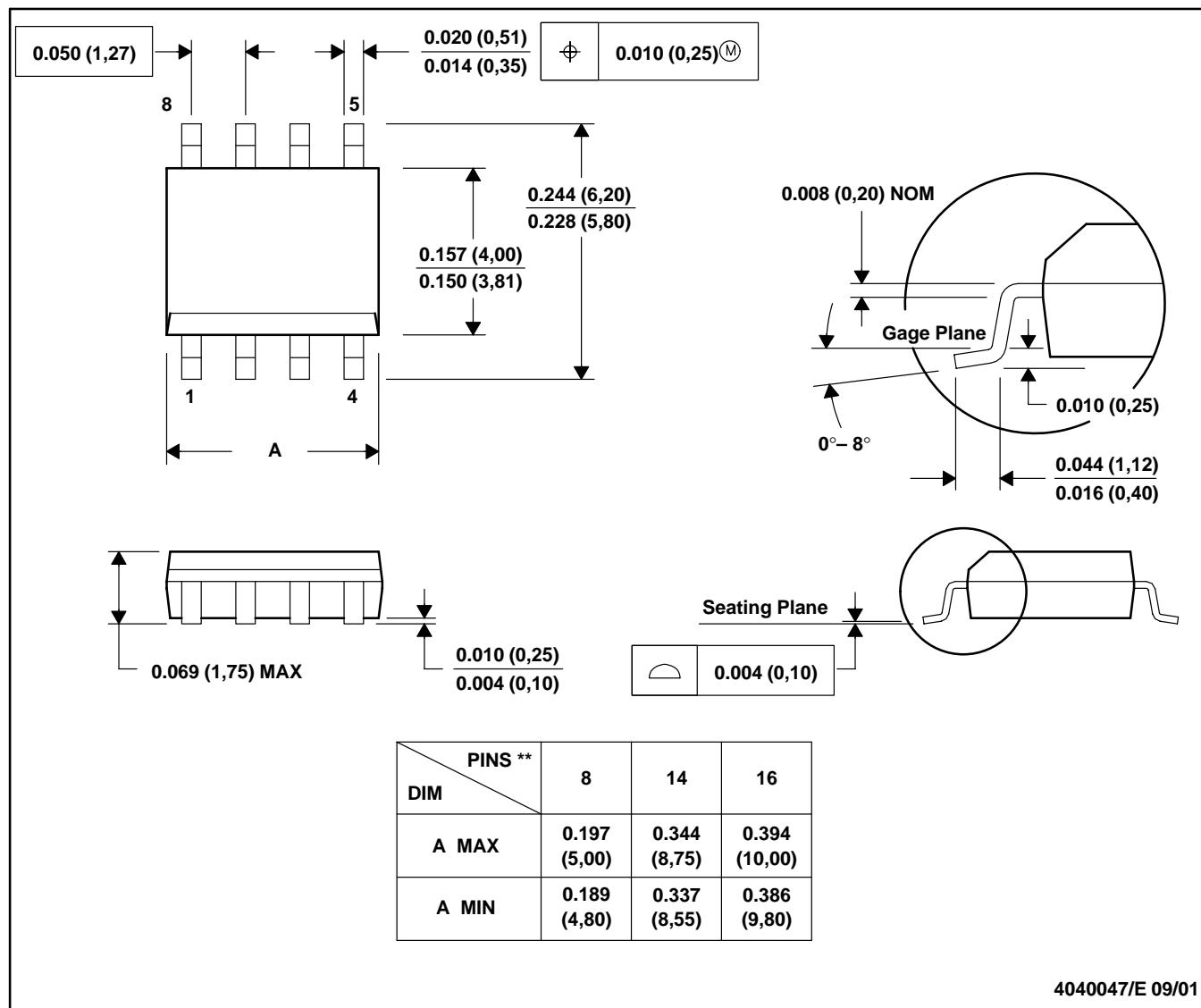
NOTES: A. All linear dimensions are in inches (millimeters).
 B. This drawing is subject to change without notice.
 C. Falls within JEDEC MS-001

PACKAGE DRAWINGS (Cont)

D (R-PDSO-G**)

8 PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion, not to exceed 0.006 (0.15).
 D. Falls within JEDEC MS-012

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
OPA602AM	OBsolete	TO-99	LMC	8		TBD	Call TI	Call TI
OPA602AM2	OBsolete	TO-99	LMC	8		TBD	Call TI	Call TI
OPA602AP	ACTIVE	PDIP	P	8	50	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type
OPA602APG4	ACTIVE	PDIP	P	8	50	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type
OPA602AU	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR
OPA602AU/2K5	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR
OPA602AU/2K5E4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR
OPA602AUE4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR
OPA602AUG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR
OPA602BM	OBsolete	TO-99	LMC	8		TBD	Call TI	Call TI
OPA602BM1	OBsolete	TO-99	LMC	8		TBD	Call TI	Call TI
OPA602BP	ACTIVE	PDIP	P	8	50	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type
OPA602BPG4	ACTIVE	PDIP	P	8	50	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type
OPA602CM	OBsolete	TO-99	LMC	8		TBD	Call TI	Call TI
OPA602SM	OBsolete	TO-99	LMC	8		TBD	Call TI	Call TI

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBsolete: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

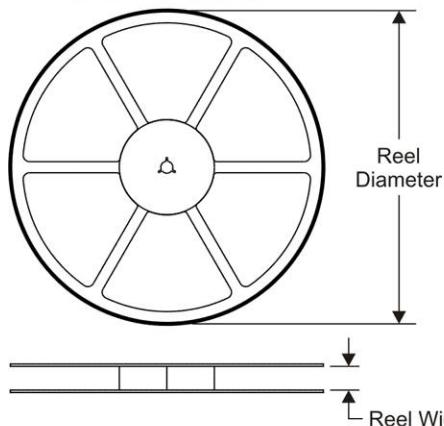
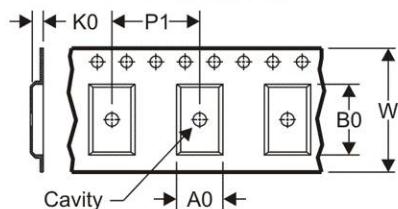
Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

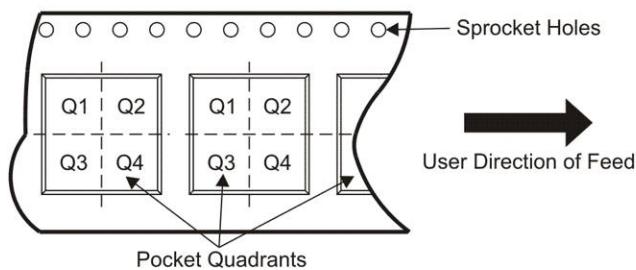
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TAPE AND REEL INFORMATION
REEL DIMENSIONS

TAPE DIMENSIONS


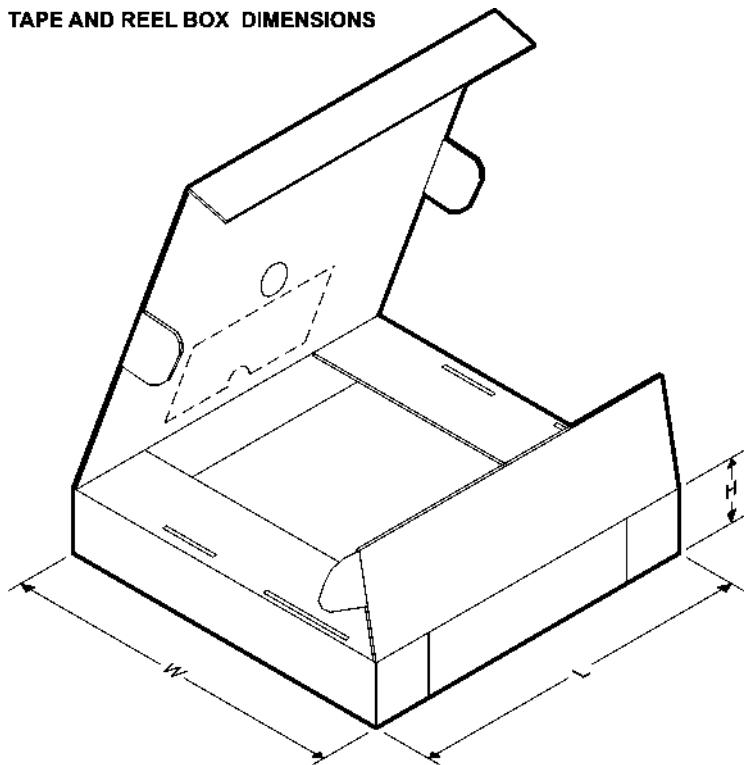
A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
OPA602AU/2K5	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
OPA602AU/2K5	SOIC	D	8	2500	346.0	346.0	29.0

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